

## PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

## CONVEYING PARTY DATA

Name	Execution Date
Richard Chu	07/22/2010
Martin Liu	07/22/2010
Chia-Hua Chu	07/22/2010
Yuan-Chih Hsieh	07/22/2010
Chung-Hsien Lin	07/22/2010
Lan-Lin Chao	07/22/2010
Chun-Wen Cheng	07/22/2010
Mingo Liu	07/22/2010

## RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12846504

## CORRESPONDENCE DATA

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PATENT  
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ATTORNEY DOCKET NUMBER:	24061.1508 / 2010-0464
NAME OF SUBMITTER:	Eric Q. Li
<b>Total Attachments: 4</b> source=24061-1508-Assignment#page1.tif source=24061-1508-Assignment#page2.tif source=24061-1508-Assignment#page3.tif source=24061-1508-Assignment#page4.tif	

# ASSIGNMENT

WHEREAS, we,

- |     |                 |    |  |
|-----|-----------------|----|--|
| (1) | Richard Chu     | of | 4F, No. 9-2, Lane 110, Qiangang Street, Shilin District<br>Taipei City 111, Taiwan, R.O.C.         |
| (2) | Martin Liu      | of | 3F, No. 7, Bao-an Road<br>Yonghe City, Tapei County 234, Taiwan, R.O.C.                            |
| (3) | Chia-Hua Chu    | of | No. 1, Lane 176, Aikou 6th Street<br>Zhubei City, Hsinchu County 302, Taiwan, R.O.C.               |
| (4) | Yuan-Chih Hsieh | of | 4F, No. 12, Lane 1007, Daxue Road<br>Hsinchu City 300, Taiwan, R.O.C.                              |
| (5) | Chung-Hsien Lin | of | 6, Creation Road, Hsinchu Science Park<br>Hsinchu, Taiwan, R.O.C.                                  |
| (6) | Lan-Lin Chao    | of | 3F, No. 113, Zihli Street<br>Sindian City, Taipei County, Taiwan, R.O.C.                           |
| (7) | Chun-Wen Cheng  | of | No. 15, Alley 11, Lane 100, Jianfeng 1st Street<br>Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (8) | Mingo Liu       | of | No. 22, Ray-Lin Road<br>Hsinchu, Taiwan, R.O.C.  |

have invented certain improvements in

# HERMETIC WAFER LEVEL PACKAGING

for which we have executed an application for Letters Patent of the United States of America,

         of even date filed herewith; and  
  X   filed on July 29, 2010 and assigned application number 12/846,504; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications

thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Richard Chu

Residence Address: 4F, No. 9-2, Lane 110, Qiangang Street, Shilin District  
Taipei City 111, Taiwan, R.O.C.

Dated: 2010/7/22

  
Inventor Signature

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Inventor Name: Martin Liu

Residence Address: 3F, No. 7, Bao-an Road  
Yonghe City, Taipei County 234, Taiwan, R.O.C.

Dated: 2010.7.22.

  
Inventor Signature

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Inventor Name: Chia-Hua Chu

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Dated: 2010/7/22

朱家華  
Inventor Signature

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Hsinchu City 300, Taiwan, R.O.C.

Dated: 2010/7/22

謝元智  
Inventor Signature

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Inventor Name: Chung-Hsien Lin

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Dated: 2010/7/22

林宗賢  
Inventor Signature

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Inventor Name: Lan-Lin Chao

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Dated: 2002/7/22

趙蘭麟  
Inventor Signature

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Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2010.07.22

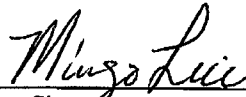
  
Inventor Signature

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Inventor Name: Mingo Liu

Residence Address: No. 22, Ray-Lin Road  
Hsinchu, Taiwan, R.O.C.

Dated: Mingo 7/27/10

  
Inventor Signature